

19th IEEE/ACM



SLIPonline.org

International Workshop on System-Level Interconnect Prediction (SLIP 2017)

co-located with ACM/IEEE Design Automation Conference

June 17 2017, Saturday

Austin Convention Center, Austin, TX

Co-sponsored by the ACM SIGDA and the IEEE Computer Society

General Chair: Tsung-Yi Ho, National Tsing Hua Univ., TW
Technical Program Chair: Shivan Hu, Michigan Tech., USA
Technical Program Co-Chair: Mustafa Badaroglu, Qualcomm Inc., USA
Finance Chair: Amlan Ganguly, Rochester Inst. of Technology, USA
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Panel Chair: Yanzhi Wang, University of Syracuse, USA
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The general technical scope of the workshop is the design, analysis, prediction, and optimization of interconnect and communication fabrics in electronic systems. The organizing committee invites original contributions to the workshop. These contributions include papers, tutorials, panels, special sessions, and posters. We accept papers based on novelty and contributions to the advancement of the field. The accepted papers will be published in the ACM and IEEE digital libraries.

- High speed chip-to-chip interconnect design
- Design and analysis of chip-package interfaces
- Power consumption of interconnects
- 3D interconnect design and prediction
- Emerging interconnect technologies
- Applications of interconnects to social, genetic, and biological systems
- Co-optimization of interconnect technology and chip design

Technical topics include but are not limited to:

- Interconnect prediction and optimization at various IC and system design stages
- System-level design for FPGAs, NOCs, reconfigurable systems
- Design, analysis, and optimization of power and clock networks
Interconnect reliability
Interconnect topologies and fabrics of multi- and many-core architectures
- Design-for-manufacturing (DFM) and yield techniques for interconnects

Submission:

We invite authors to submit papers of 4 to 8 pages, double-columned, 9pt or 10pt font in ACM proceedings format available at

www.acm.org/sigs/publications/proceedings-templates

To permit double blind review, all papers must remove author information (submissions with author information will be rejected). Authors should submit papers electronically: <http://www.easychair.org/conferences/?conf=slip17>

(New) Student Awards:

Provided by the IEEE Computer Society's Technical Committee on VLSI (TCVLSI), the Best Student Paper Award will be awarded for a SLIP2017 paper whose first author is a student. In addition, limited student travel grants of \$250 are available. Details will follow on the website.

(New) Selected papers will be invited to the special issue of Integration, the VLSI Journal

Format:

The workshop includes keynotes, regular paper sessions, interactive panels, tutorials, invited talks, and interactive poster sessions. Our program also includes lunch, refreshments, and a traditional social dinner with fun elements.

Important Dates:

Abstract Registration: Mar 11, 2017
Paper Submission: Apr 1, 2017
Author Notification: April 22, 2017
Final Version Upload: May 1, 2017